

Features







1 Molex "Mirror Mezz" Licensed Second Source

- 2 High Speed Transmission (56+Gbps NRZ / 112+Gbps PAM4)
- **3 OAM Specified Connector**
- 4 High Pin Count, High Density: 688pos. (172DPs/in²)
- **5 Hermaphroditic Connector**
- 6 Stub-less 2-point Contact Design
- 7 Protective Housing that Encapsulates the Contact Tips **Prevents Warping During Mating**

Ton Stiffener Board

Contact Design

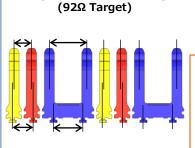
Used in OAM* (OCP Accelerator Module)

Specifications

2-point Contact

Stub-less Design

- ·Superior SI Performance ·2-point Contact for
- **Enhanced Reliability**
- ·Wiping Amount: 1.5mm Max.



Impedance Matching

Pitch differs from contact portion and mounted portion for impedance optimization.



(2.5mm + 2.5mm)688pos. 172 Differential Pairs

1	
	OAM* Board
[bood]	Love

Rated Current	1.2A
Rated Voltage	30V AC/DC
Operating Temperature	-55 to +105℃
Contact Resistance*	30mΩ Max.
Withstanding Voltage	500V DC for 1min.
Insulation Resistance	1000MΩ (500V DC)
Mating Durability	100 times
Impedance	92Ω

*Includes conductor resistance.

- -Cross mates with Molex's Mirror Mezz.
- -No. of Pos. : 688pos.



*OAM = OCP (Open Computer Project) Accelerator Module